T-1 (3mm) SOLID STATE LAMP

Part Number: L-7104GD-12V Green

ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- Low power consumption.
- Popular T-1 diameter package.
- General purpose leads
- Reliable and rugged.
- Long life solid state reliability.
- Available on tape and reel.
- 12V internal resistor.
- RoHS compliant.

Description

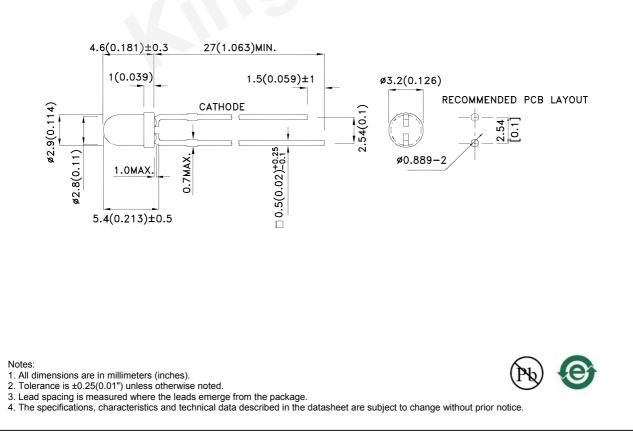
The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



SPEC NO: DSAC2577 APPROVED: WYNEC REV NO: V.9B CHECKED: Allen Liu DATE: FEB/10/2014 DRAWN: L.Q.Xie PAGE: 1 OF 6 ERP: 1101029230

Selection Guide

Ociection Oulde					
Part No.	Dice	Lens Type	lv (mcd) [2] V= 12V		Viewing Angle [1]
			Min.	Тур.	201/2
L-7104GD-12V	Green (GaP)	Green Diffused	6	15	40°

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	565		nm	VF=12V
λD [1]	Dominant Wavelength	Green	568		nm	VF=12V
Δλ1/2	Spectral Line Half-width	Green	30		nm	VF=12V
lf	Forward Current	Green	8.5	11.5	mA	VF=12V
lr	Reverse Current	Green		10	uA	VR = 5V

Note:

1.Wavelength: +/-1nm.

2. Wavelength value is traceable to the CIE127-2007 compliant national standards.

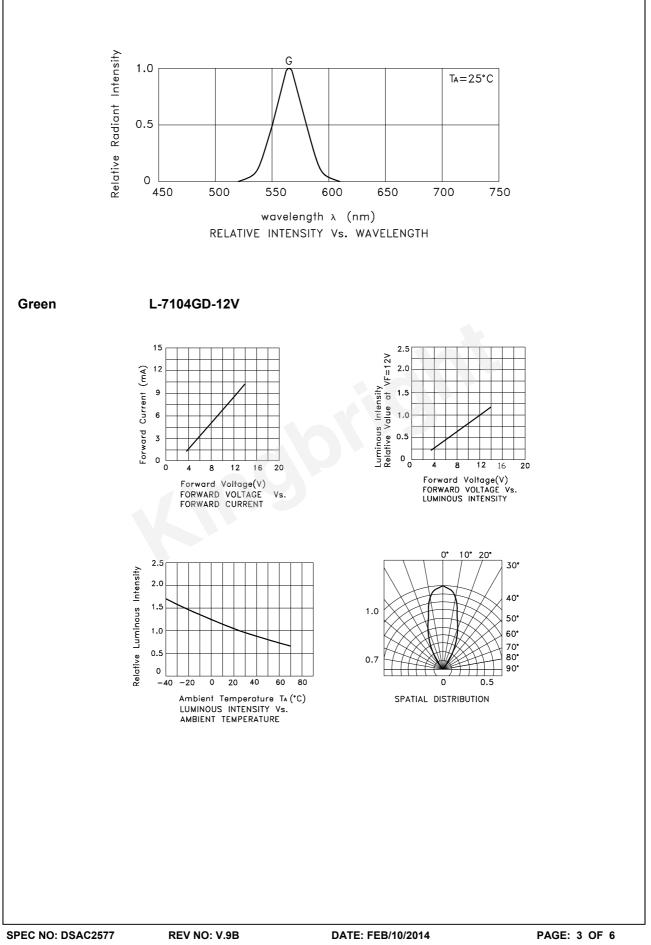
Absolute Maximum Ratings at TA=25°C

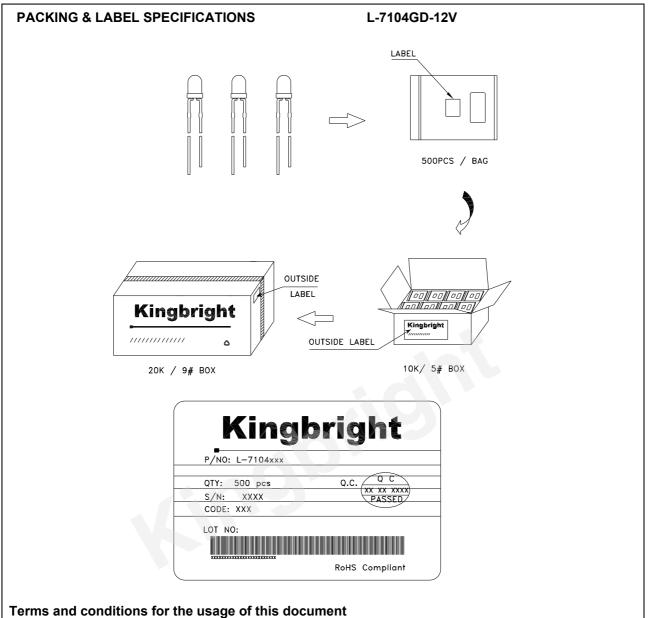
Parameter	Green	Units	
Power dissipation	120	mW	
Forward Voltage	14	V	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +70°C		
Storage Temperature	-40°C To +85°C		
Lead Solder Temperature [1]	260°C For 3 Seconds		
Lead Solder Temperature [2]	260°C For 5 Seconds		

Notes:

1. 2mm below package base.

2. 5mm below package base.

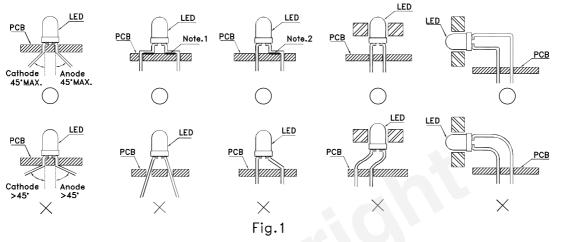




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- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
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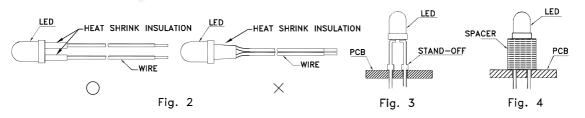
PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



" \bigcirc " Correct mounting method "imes" Incorrect mounting method

- 2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
- 3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 4. Maintain a minimum of 3mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

